



N-Channel 40 V (D-S) MOSFET

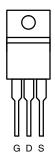
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)	
40	0.0033 at V _{GS} = 10 V	90	87	
	0.0041 at $V_{GS} = 4.5 \text{ V}$	90	67	

FEATURES

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



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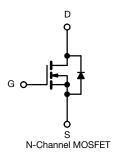


Top View

Ordering Information: SUP90N04-3m3P-GE3 (Lead (Pb)-free and Halogen-free)

APPLICATIONS

- **Power Supply**
 - Secondary Synchronous Rectification
- DC/DC Converter



ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	40	V		
Gate-Source Voltage	V _{GS}	± 20	¬		
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	1_	90 ^d		
Continuous Diam Current (1) = 130 C)	T _C = 70 °C	I _D	90 ^d	A	
Pulsed Drain Current	I _{DM}	160	7		
Avalanche Current	I _{AS}	60			
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	180	mJ	
Maximum Barras Biratinatian	T _C = 25 °C	В	125 ^b	w	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	$ P_{D}$	3.1	vv	
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)	R _{thJC}	1	C/ VV	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{DS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	40			5 V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.5		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V _{DS} = 40 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 125 °C			50		
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250	1	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Drain-Source On-State Resistance ^a	D	V _{GS} = 10 V, I _D = 22 A		0.0027	0.0033	0	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0034	0.0041	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		169		S	
Dynamic ^b							
Input Capacitance	C _{iss}			5286		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$		705			
Reverse Transfer Capacitance	C _{rss}			283			
Total Gate Charge ^c	Q_g			87	131		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		15.3		nC	
Gate-Drain Charge ^c	Q_{gd}			12.2			
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.7	5.4	Ω	
Turn-On Delay Time ^c	t _{d(on)}			11	20		
Rise Time ^c	t _r	V_{DD} = 20 V, R_L = 2 Ω		7	14		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		45	68	ns	
Fall Time ^c	t _f			7	14		
Drain-Source Body Diode Ratings ar	nd Characteris	stics T _C = 25 °C ^b					
Continuous Current	Is	•			90		
Pulsed Current	I _{SM}				160	Α	
Forward Voltage ^a	V _{SD}	I _F = 10 A, V _{GS} = 0 V		0.72	1.2	V	
Reverse Recovery Time	t _{rr}			42	63	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 10 A, dI/dt = 100 A/μs		2.5	3.8	Α	
Reverse Recovery Charge	Q _{rr}			52	78	nC	

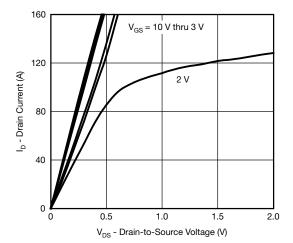
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

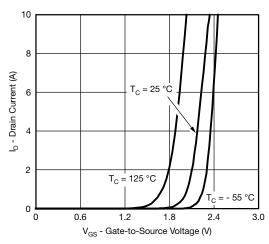
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



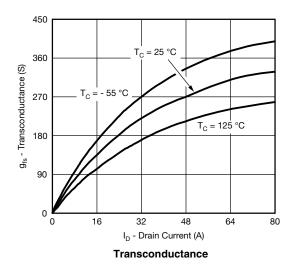
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

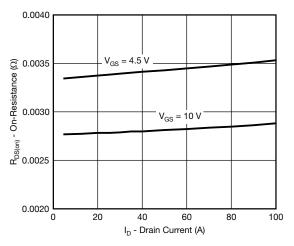


Output Characteristics

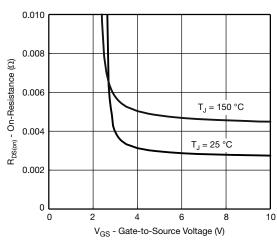


Transfer Characteristics

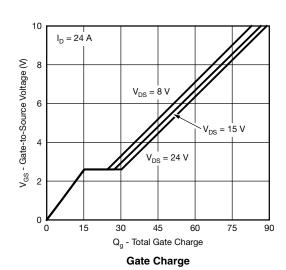




On-Resistance vs. Drain Current

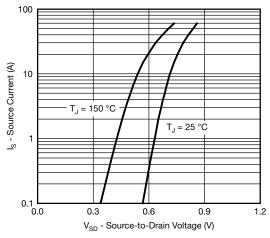


On-Resistance vs. Gate-to-Source Voltage

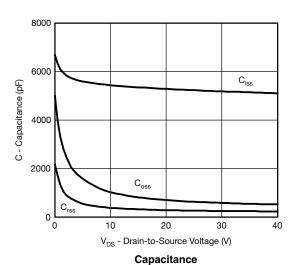


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Source-Drain Diode Forward Voltage

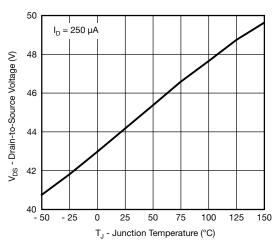


2.0 I_D = 22 A $V_{GS} = 10 \text{ V}$ R_{DS(on)} - On-Resistance (Normalized) 1.7 1.4 $V_{GS} = 4.5 \text{ V}$ 0.5 - 50 - 25 100 125 75 T_J - Junction Temperature (°C)

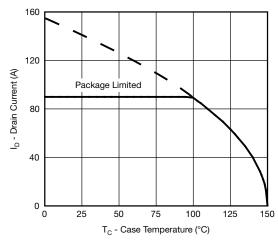
On-Resistance vs. Junction Temperature

2.2 1.7 $V_{GS(th)}(V)$ $I_D = 250 \,\dot{\mu}A$ 0.7 0.2 - - 50 - 25 50 75 100 125 150 T_.I - Junction Temperature (°C)

Threshold Voltage

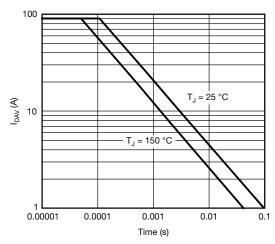


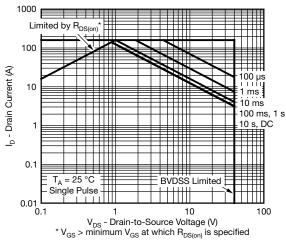
Drain Source Breakdown vs. Junction Temperature



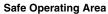
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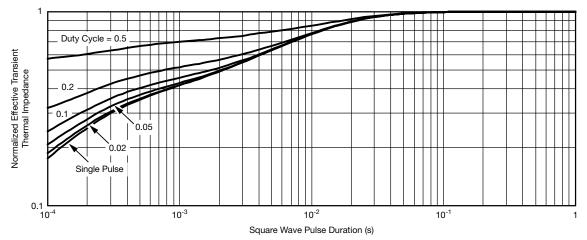
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time

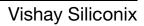




Normalized Thermal Transient Impedance, Junction-to-Case

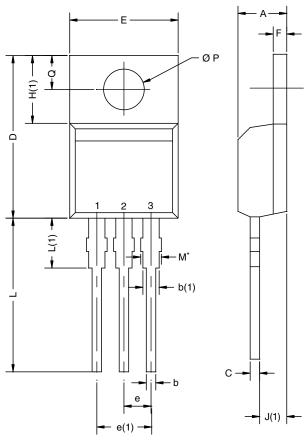
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Document Number: 65902 S11-2042-Rev. B, 17-Oct-11





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- e	(1) -	
		D2

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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